



PROCESS CHANGE NOTIFICATION PCN0512 IMPLEMENTING STANDARD SUMITOMO-G600 SERIES MOLD COMPOUND FOR PLCC PACKAGES

Change Description:

Altera will implement a standard Sumitomo-G600 series mold compound on its Plastic J-Lead Chip Carrier (PLCC) packages. All devices in PLCC packages assembled at ASE Malaysia and Amkor Philippines that are currently using Nitto's MP8000 series mold material will be molded with Sumitomo-G600 series mold compound. This mold material had been qualified by Altera. This change does not affect the form, fit, or function of the devices and does not change the current moisture sensitivity level of this package.

Reason for Change:

Altera is standardizing the mold compound of its Pb-free and standard products in PLCC packages to this Pb-free compliant mold compound.

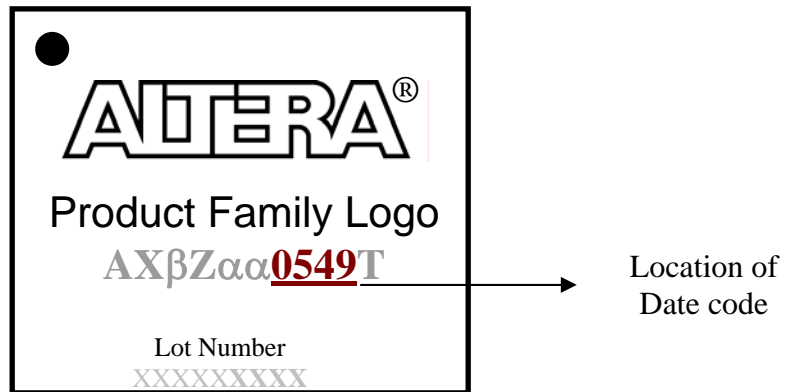
Products Affected:

The affected product lines are listed in Table 1.

Product Traceability and Transition Dates:

This change will be implemented in the December 2005 timeframe. Customers may receive products molded with Sumitomo-G600 series mold compound starting with the topside mark date code of 0549, as shown in Figure 1.

Figure 1. Example of Date Code Marking



Contact:

For more information on this change, please contact your local Altera[®] sales representative or Altera Customer Quality Engineering at customer-quality@altera.com.

Table 1 – Affected OPN

Package	Pin Count	Product Line
PLCC	20	EPC1 EPC1064 EPC1064V EPC1213 EPC1441 EPC2
	28	EP600I EP610 EP610I
	44	EP900I EP910 EP910I EPM3032A EPM3064A EPM7032 EPM7032AE EPM7032B EPM7032S EPM7064 EPM7064AE EPM7064S
	68	EP1800I EP1810 EPM7064 EPM7096
	84	EPF10K10 EPF8282A EPF8452A EPF8636A EPM7064 EPM7064S EPM7096 EPM7128A EPM7128AE EPM7128E EPM7128S EPM7160E EPM7160S EPM9320 EPM9320A